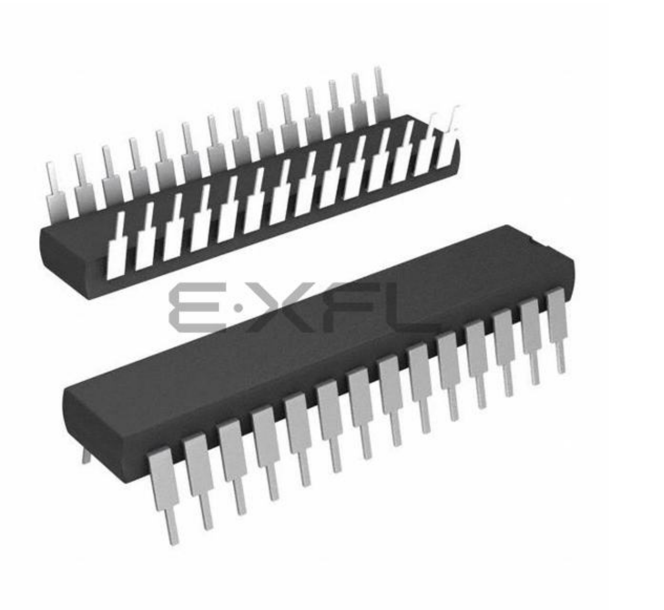


Welcome to E-XFL.COM

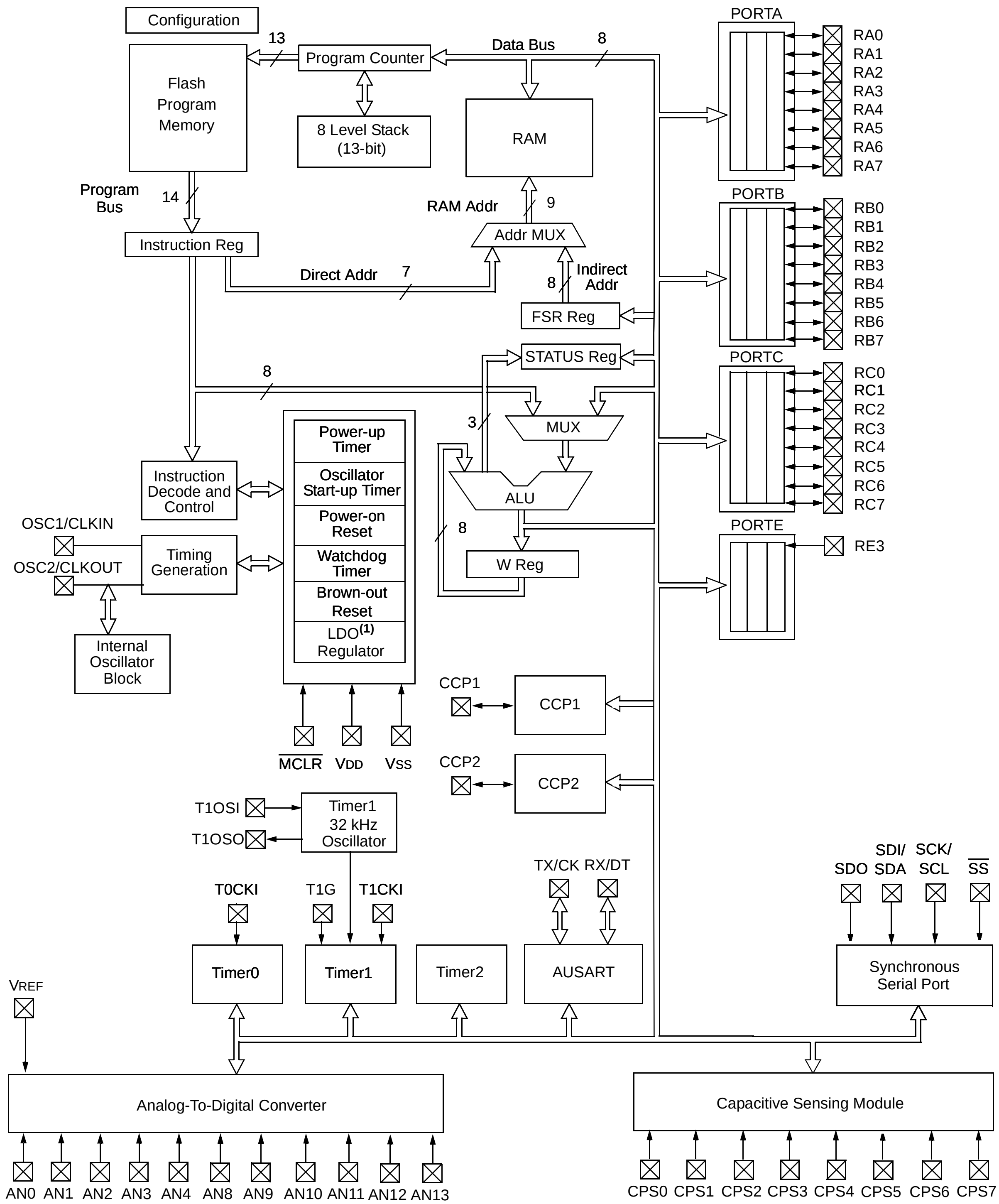
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f722a-i-sp

FIGURE 1-1: PIC16(L)F722A/723A BLOCK DIAGRAM



Note 1: PIC16F722A/723A only.

FIGURE 2-4: PIC16(L)F723A SPECIAL FUNCTION REGISTERS

File Address

Bank 0		Bank 1		Bank 2		Bank 3	
Indirect addr.(*)	00h	Indirect addr.(*)	80h	Indirect addr.(*)	100h	Indirect addr.(*)	180h
TMR0	01h	OPTION	81h	TMR0	101h	OPTION	181h
PCL	02h	PCL	82h	PCL	102h	PCL	182h
STATUS	03h	STATUS	83h	STATUS	103h	STATUS	183h
FSR	04h	FSR	84h	FSR	104h	FSR	184h
PORTA	05h	TRISA	85h		105h	ANSELA	185h
PORTB	06h	TRISB	86h		106h	ANSELB	186h
PORTC	07h	TRISC	87h		107h		187h
	08h		88h	CPSCON0	108h		188h
PORTE	09h	TRISE	89h	CPSCON1	109h		189h
PCLATH	0Ah	PCLATH	8Ah	PCLATH	10Ah	PCLATH	18Ah
INTCON	0Bh	INTCON	8Bh	INTCON	10Bh	INTCON	18Bh
PIR1	0Ch	PIE1	8Ch	PMDATL	10Ch	PMCON1	18Ch
PIR2	0Dh	PIE2	8Dh	PMADRL	10Dh	Reserved	18Dh
TMR1L	0Eh	PCON	8Eh	PMDATH	10Eh	Reserved	18Eh
TMR1H	0Fh	T1GCON	8Fh	PMADRH	10Fh	Reserved	18Fh
T1CON	10h	OSCCON	90h		110h		190h
TMR2	11h	OSCTUNE	91h		111h		191h
T2CON	12h	PR2	92h		112h		192h
SSPBUF	13h	SSPADD/SSPMSK	93h		113h		193h
SSPCON	14h	SSPSTAT	94h		114h		194h
CCPR1L	15h	WPUB	95h		115h		195h
CCPR1H	16h	IOCB	96h		116h		196h
CCP1CON	17h		97h		117h		197h
RCSTA	18h	TXSTA	98h		118h		198h
TXREG	19h	SPBRG	99h		119h		199h
RCREG	1Ah		9Ah		11Ah		19Ah
CCPR2L	1Bh		9Bh		11Bh		19Bh
CCPR2H	1Ch	APFCON	9Ch		11Ch		19Ch
CCP2CON	1Dh	FVRCON	9Dh		11Dh		19Dh
ADRES	1Eh		9Eh		11Eh		19Eh
ADCON0	1Fh	ADCON1	9Fh		11Fh		19Fh
General Purpose Register 96 Bytes	20h–7Fh	General Purpose Register 80 Bytes	A0h–EFh	General Purpose Register 16 Bytes	120h–12Fh		1A0h–1EFh
					130h–16Fh		
		Accesses 70h-7Fh	F0h–FFh	Accesses 70h-7Fh	170h–17Fh	Accesses 70h-7Fh	1F0h–1FFh

Legend: (shaded) = Unimplemented data memory locations, read as '0'.
* = Not a physical register.

TABLE 3-1: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	x	1	1	Power-on Reset or LDO Reset
0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
1	1	1	0	$\overline{\text{MCLR}}$ Reset during Sleep or interrupt wake-up from Sleep

TABLE 3-2: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	0001 1xxx	---- --0x
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	000u uuuu	---- --uu
$\overline{\text{MCLR}}$ Reset during Sleep	0000h	0001 0uuu	---- --uu
WDT Reset	0000h	0000 1uuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	0000h	0001 1uuu	---- --u0
Interrupt Wake-up from Sleep	PC + 1(1)	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

6.3.4 PIN DESCRIPTIONS AND DIAGRAMS

Each PORTB pin is multiplexed with other functions. The pins and their combined functions are briefly described here. For specific information about individual functions such as the SSP, I^2C or interrupts, refer to the appropriate section in this data sheet.

6.3.4.1 RB0/AN12/CPS0/INT

Figure 6-7 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input
- External edge triggered interrupt

6.3.4.2 RB1/AN10/CPS1

Figure 6-8 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input

6.3.4.3 RB2/AN8/CPS2

Figure 6-8 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input

6.3.4.4 RB3/AN9/CPS3/CCP2

Figure 6-9 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input
- Capture 2 input, Compare 2 output, and PWM2 output

Note:	CCP2 pin location may be selected as RB3 or RC1.

6.3.4.5 RB4/AN11/CPS4

Figure 6-8 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input

6.3.4.6 RB5/AN13/CPS5/T1G

Figure 6-10 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- Analog input for the ADC
- Capacitive sensing input
- Timer1 gate input

6.3.4.7 RB6/ICSPCLK

Figure 6-11 shows the diagram for this pin. This pin is configurable to function as one of the following:

- a general purpose I/O
- In-Circuit Serial Programming clock

6.3.4.8 RB7/ICSPDAT

Figure 6-12 shows the diagram for this pin. This pin is configurable to function as one of the following:

- General purpose I/O
- In-Circuit Serial Programming data

FIGURE 6-7: BLOCK DIAGRAM OF RB0

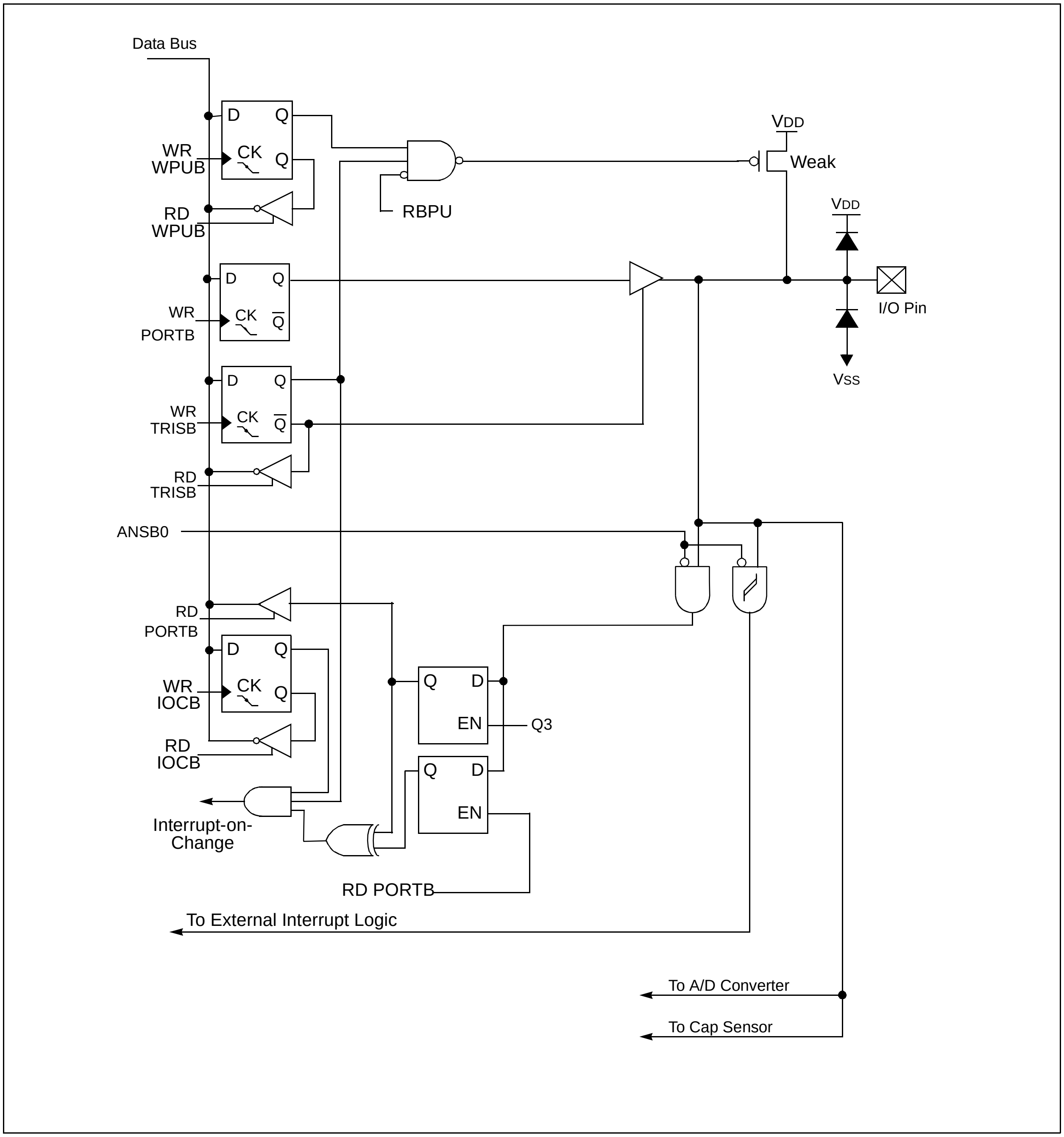
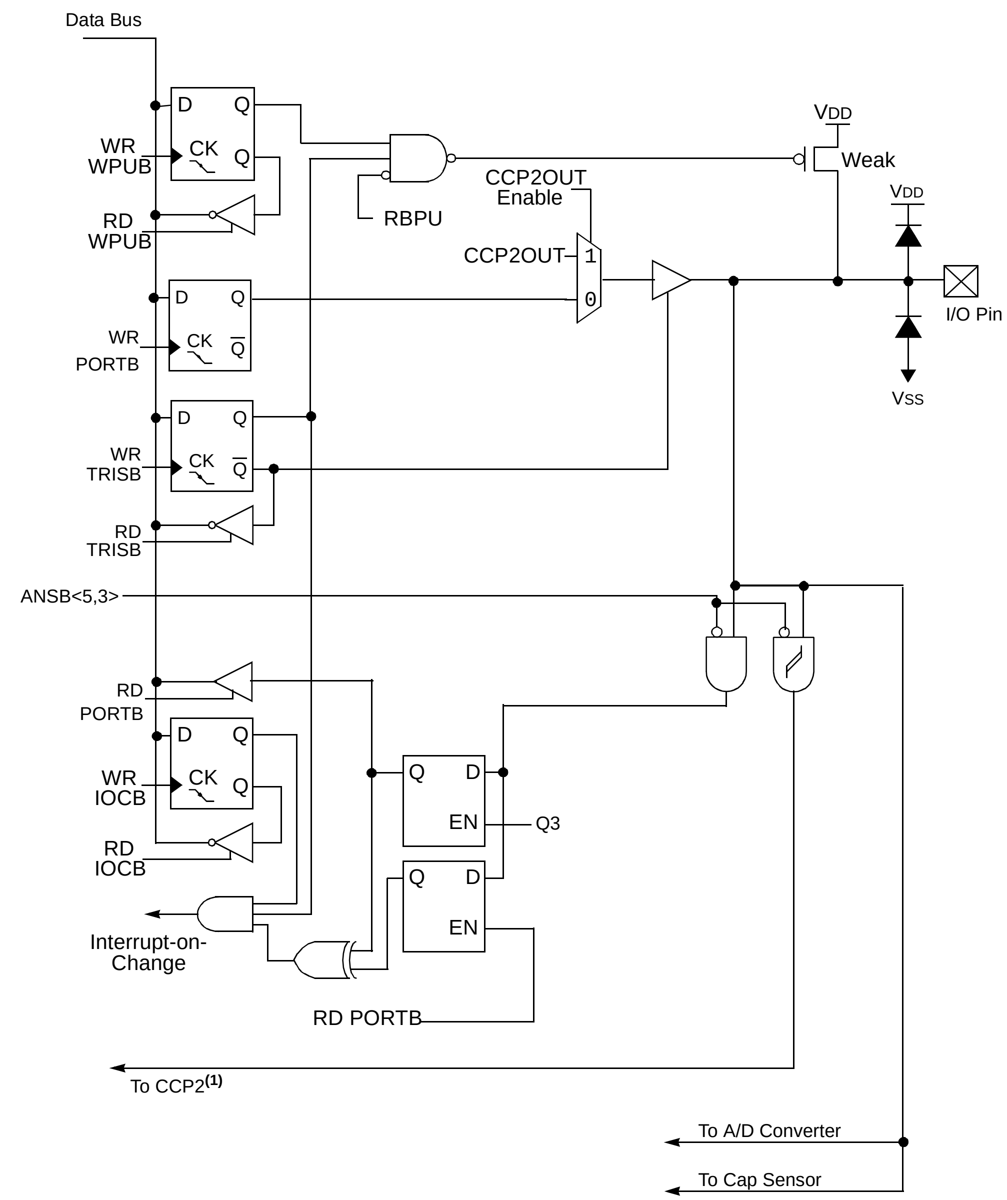


FIGURE 6-9: BLOCK DIAGRAM OF RB3



Note 1: CCP2 input is controlled by CCP2SEL in the APFCON register.

FIGURE 6-15: BLOCK DIAGRAM OF RC2

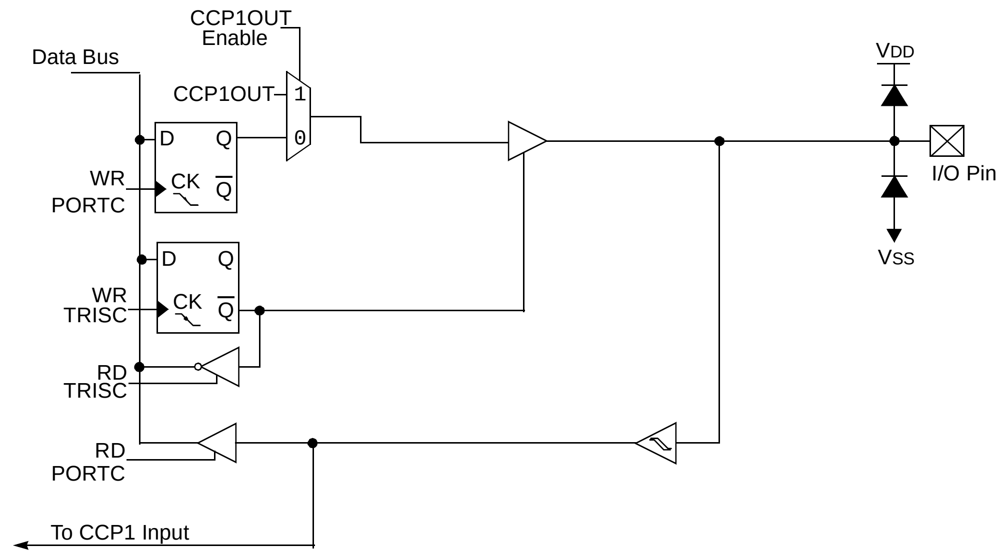
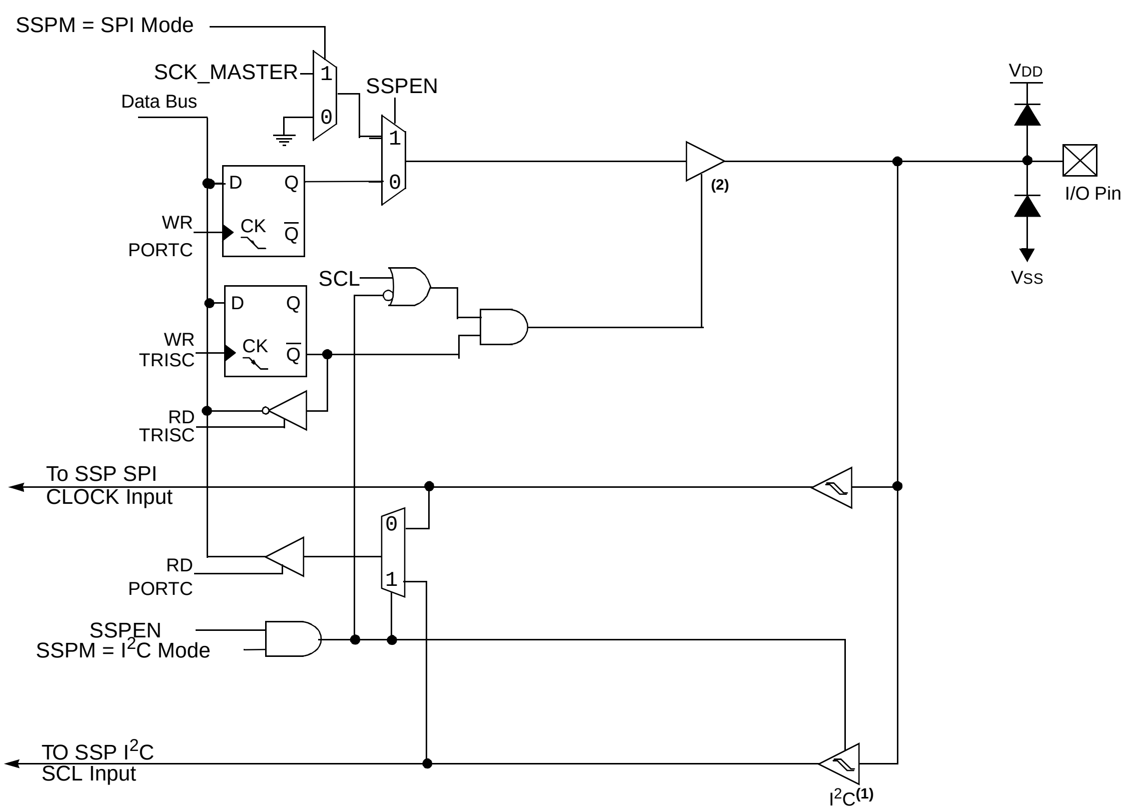


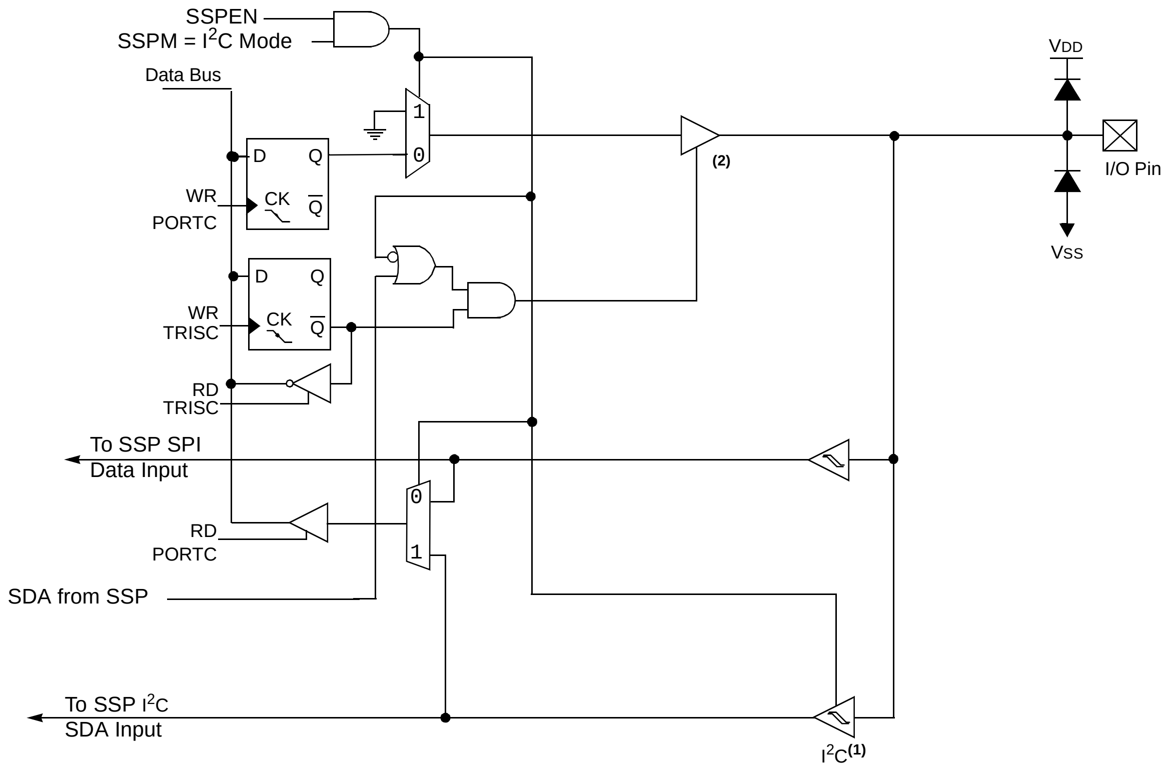
FIGURE 6-16: BLOCK DIAGRAM OF RC3



Note 1: I²C Schmitt Trigger has special input levels.

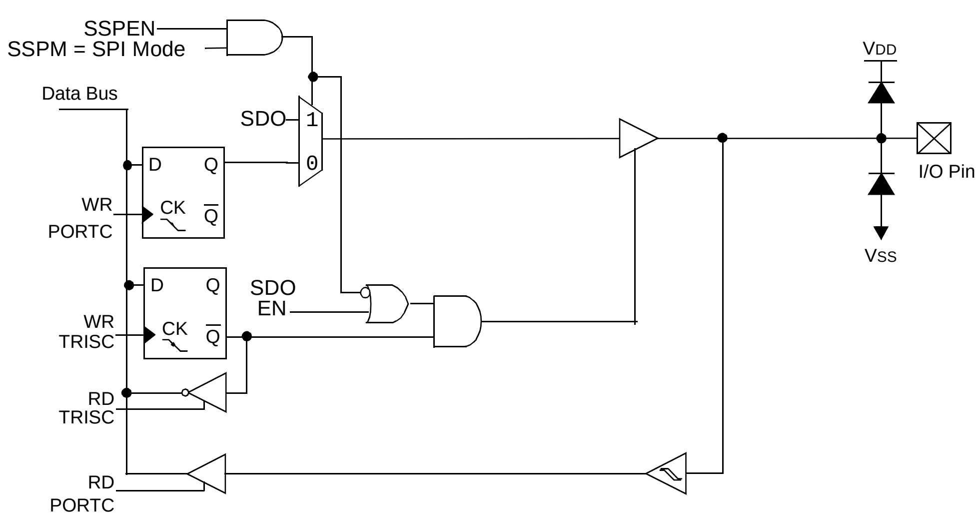
2: I²C Slew Rate limiting controlled by SMP bit of SSPSTAT register.

FIGURE 6-17: BLOCK DIAGRAM OF RC4



Note 1: I^2C Schmitt Trigger has special input levels.
2: I^2C Slew Rate limiting controlled by SMP bit of SSPSTAT register.

FIGURE 6-18: BLOCK DIAGRAM OF RC5



9.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 9-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 9-3. **The maximum recommended impedance for analog sources is 10 kΩ**. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 9-1 may be used. This equation assumes that 1/2 LSb error is used (256 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 9-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $5.0V$ V_{DD}

$$
\begin{aligned}
T_{ACQ} &= \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient} \\
&= T_{AMP} + T_C + T_{COFF} \\
&= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]
\end{aligned}
$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD} \text{ charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD} \text{ charge response to } V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) \quad ;\text{combining [1] and [2]}$$

Note: *Where n = number of bits of the ADC.*

Solving for T_C:

$$
\begin{aligned}
T_C &= -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/511) \\
&= -10pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.001957) \\
&= 1.12\mu s
\end{aligned}
$$

Therefore:

$$
\begin{aligned}
T_{ACQ} &= 2\mu s + 1.12\mu s + [(50°C - 25°C)(0.05\mu s/°C)] \\
&= 4.42\mu s
\end{aligned}
$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

TABLE 9-2: SUMMARY OF ASSOCIATED ADC REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	85
ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	ADREF1	ADREF0	86
ANSELA	—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	44
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	53
ADRES	A/D Result Register Byte								86
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	115
FVRCON	FVRRDY	FVREN	—	—	—	—	ADFVR1	ADFVR0	90
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	36
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	37
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	39
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	43
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	52

Legend: x = unknown, u = unchanged, – = unimplemented read as ‘0’, q = value depends on condition. Shaded cells are not used for ADC module.

TABLE 12-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	53
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	115
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	115
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	36
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	37
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	39
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	52
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								99
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								99
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	52
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	62
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	—	TMR1ON	103
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GSS1	T1GSS0	104

Legend: x = unknown, u = unchanged, – = unimplemented, read as ‘0’. Shaded cells are not used by the Timer1 module.

16.0 ADDRESSABLE UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (AUSART)

The Addressable Universal Synchronous Asynchronous Receiver Transmitter (AUSART) module is a serial I/O communications peripheral. It contains all the clock generators, shift registers and data buffers necessary to perform an input or output serial data transfer independent of device program execution. The AUSART, also known as a Serial Communications Interface (SCI), can be configured as a full-duplex asynchronous system or half-duplex synchronous system. Full-Duplex mode is useful for communications with peripheral systems, such as CRT terminals and personal computers. Half-Duplex Synchronous mode is intended for communications with peripheral devices, such as A/D or D/A integrated circuits, serial EEPROMs or other microcontrollers. These devices typically do not have internal clocks for baud rate generation and require the external clock signal provided by a master synchronous device.

The AUSART module includes the following capabilities:

- Full-duplex asynchronous transmit and receive
- Two-character input buffer
- One-character output buffer
- Programmable 8-bit or 9-bit character length
- Address detection in 9-bit mode
- Input buffer overrun error detection
- Received character framing error detection
- Half-duplex synchronous master
- Half-duplex synchronous slave
- Sleep operation

Block diagrams of the AUSART transmitter and receiver are shown in Figure 16-1 and Figure 16-2.

FIGURE 16-1: AUSART TRANSMIT BLOCK DIAGRAM

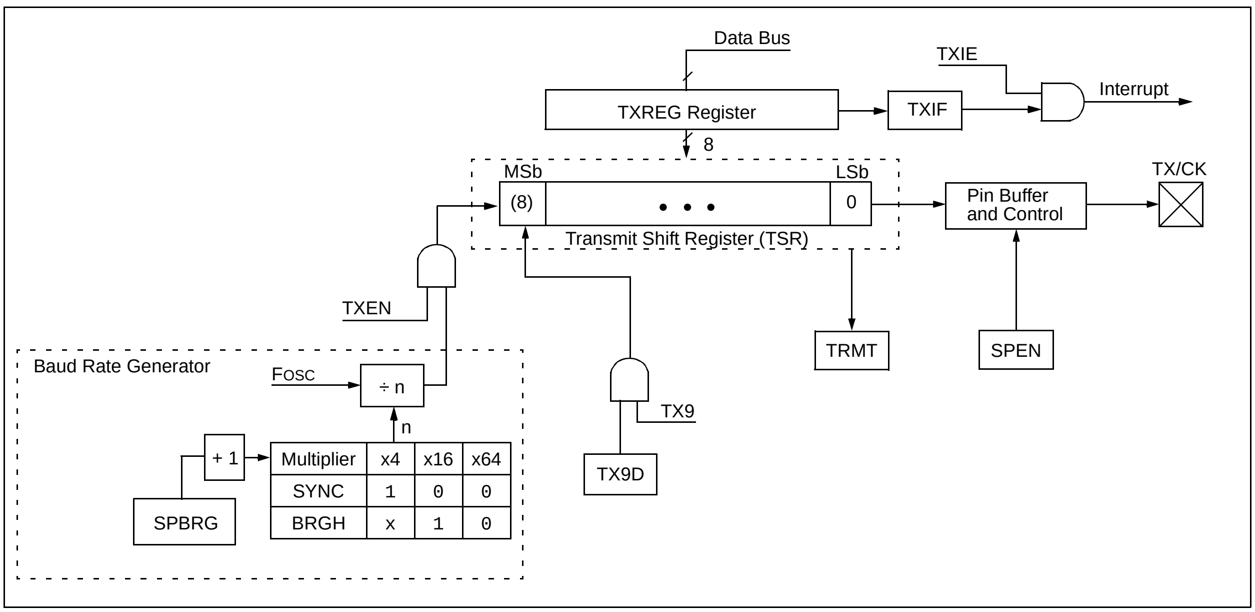


TABLE 16-2: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCREG	AUSART Receive Data Register								0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for asynchronous reception.

REGISTER 17-2: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (SPI MODE)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	$D/\overline{A}$	P	S	$R/\overline{W}$	UA	BF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **SMP**: SPI Data Input Sample Phase bit
SPI Master mode:
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave mode:
SMP must be cleared when SPI is used in Slave mode

bit 6 **CKE**: SPI Clock Edge Select bit
SPI mode, CKP = 0:
1 = Data stable on rising edge of SCK
0 = Data stable on falling edge of SCK
SPI mode, CKP = 1:
1 = Data stable on falling edge of SCK
0 = Data stable on rising edge of SCK

bit 5 **$D/\overline{A}$:** Data/$\overline{\text{Address}}$ bit
Used in I^2C mode only.

bit 4 **P:** Stop bit
Used in I^2C mode only.

bit 3 **S:** Start bit
Used in I^2C mode only.

bit 2 **$R/\overline{W}$:** Read/$\overline{\text{Write}}$ Information bit
Used in I^2C mode only.

bit 1 **UA:** Update Address bit
Used in I^2C mode only.

bit 0 **BF**: Buffer Full Status bit
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

22.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

22.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

22.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

22.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

23.1 DC Characteristics: PIC16(L)F722A/723A-I/E (Industrial, Extended)

PIC16LF722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722A/723A			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16LF722A/723A	1.8 1.8 2.3 2.5	— — — —	3.6 3.6 3.6 3.6	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D001		**PIC16F722A/723A**	1.8 1.8 2.3 2.5	— — — —	5.5 5.5 5.5 5.5	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D002*	VDR	**RAM Data Retention Voltage(1)**					
		PIC16LF722A/723A	1.5	—	—	V	Device in Sleep mode
D002*		**PIC16F722A/723A**	1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**					
		PIC16LF722A/723A	—	0.8	—	V	Device in Sleep mode
		PIC16F722A/723A	—	1.7	—	V	Device in Sleep mode
D003	VFVR	**Fixed Voltage Reference Voltage, Initial Accuracy**	-5.5 -5.5 -5.5	— — —	5.5 5.5 5.5	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 85°C
			-6 -6 -6	— — —	6 6 6	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 125°C
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 3.2 “Power-on Reset (POR)”** for details.

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

23.5 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θ_{JA}	Thermal Resistance Junction to Ambient	60.0	°C/W	28-pin SPDIP package
			69.7	°C/W	28-pin SOIC package
			71.0	°C/W	28-pin SSOP package
			52.5	°C/W	28-pin UQFN 4x4mm package
			30.0	°C/W	28-pin QFN 6x6mm package
TH02	θ_{JC}	Thermal Resistance Junction to Case	29.0	°C/W	28-pin SPDIP package
			18.9	°C/W	28-pin SOIC package
			24.0	°C/W	28-pin SSOP package
			16.7	°C/W	28-pin UQFN 4x4mm package
			5.0	°C/W	28-pin QFN 6x6mm package
TH03	T_{JMAX}	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = $P_{INTERNAL}$ + $P_{I/O}$
TH05	$P_{INTERNAL}$	Internal Power Dissipation	—	W	$P_{INTERNAL}$ = I_{DD} x V_{DD} (1)
TH06	$P_{I/O}$	I/O Power Dissipation	—	W	$P_{I/O} = \Sigma (I_{OL} * V_{OL}) + \Sigma (I_{OH} * (V_{DD} - V_{OH}))$
TH07	P_{DER}	Derated Power	—	W	$P_{DER} = PD_{MAX} (T_J - T_A)/\theta_{JA}$ (2)

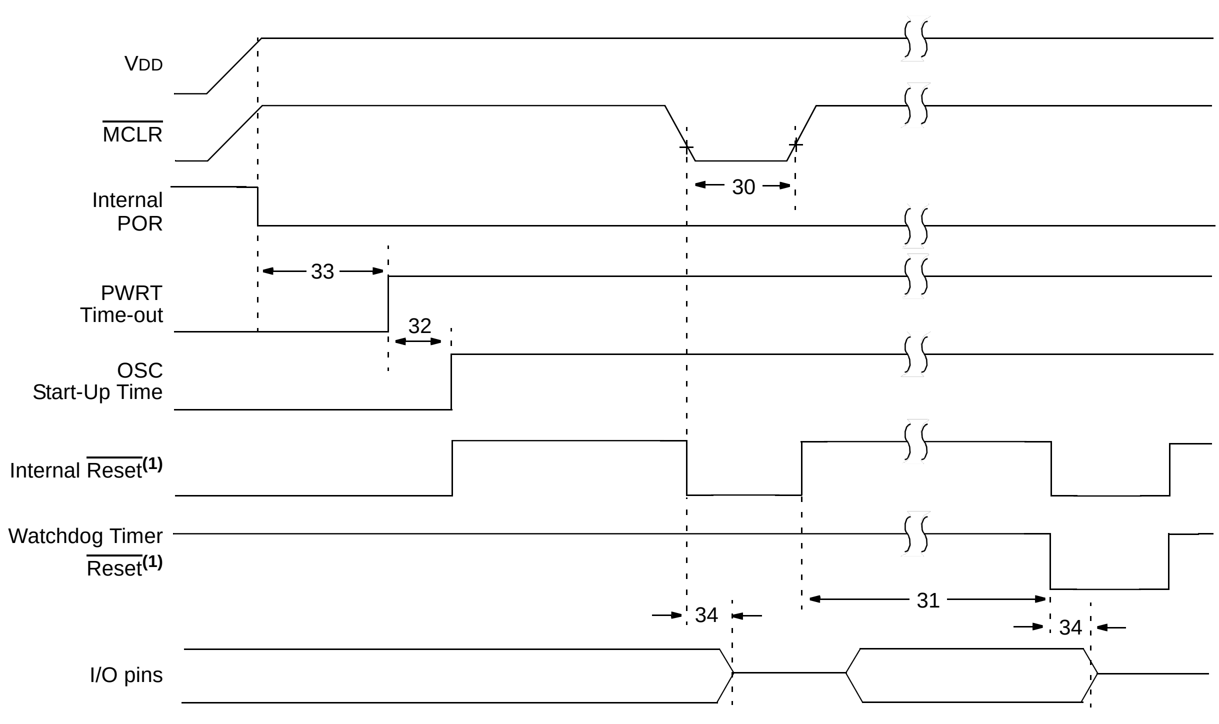
Note 1: I_{DD} is current to run the chip alone without driving any load on the output pins.
2: T_A = Ambient Temperature
3: T_J = Junction Temperature

TABLE 23-3: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	Fosc↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	Fosc↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18	TioR	Port output rise time(2)	— —	40 15	72 32	ns	VDD = 2.0V VDD = 3.3-5.0V
OS19	TioF	Port output fall time(2)	— —	28 15	55 30	ns	VDD = 2.0V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Trbp	PORTB interrupt-on-change new input level time	TCY	—	—	ns	

* These parameters are characterized but not tested.
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.
Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.
2: Includes OSC2 in CLKOUT mode.

FIGURE 23-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note 1: Asserted low.

FIGURE 24-12: PIC16LF722A/723A TYPICAL IDD vs. FOSC OVER VDD, HS MODE

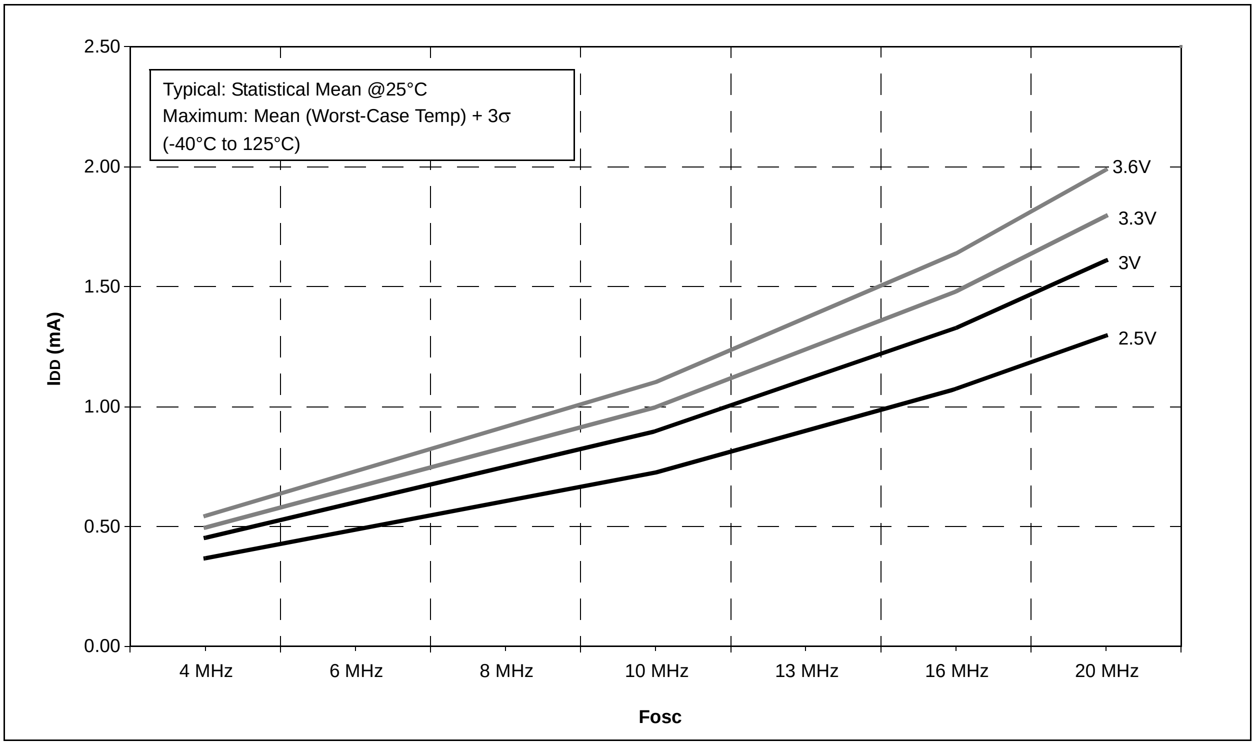
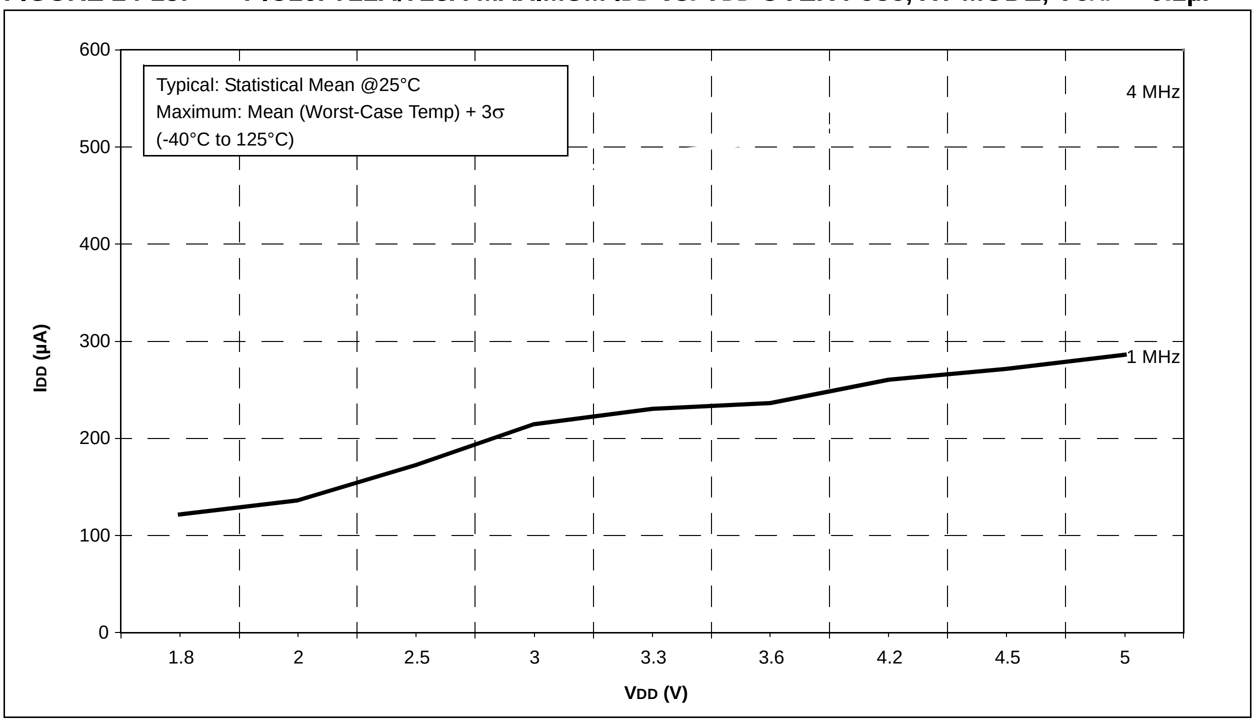
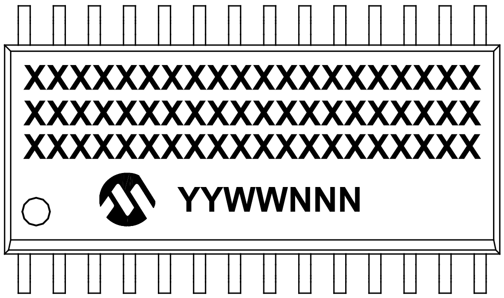


FIGURE 24-13: PIC16F722A/723A MAXIMUM IDD vs. VDD OVER FOSC, XT MODE, VCAP = 0.1μF

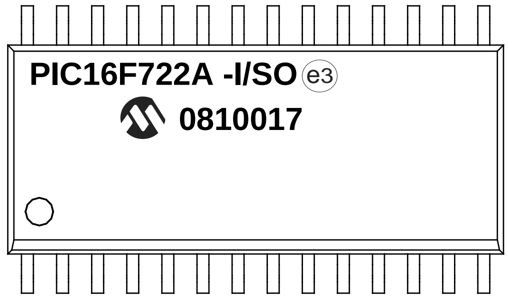


25.1 Package Marking Information (Continued)

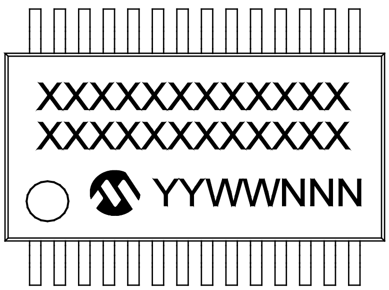
28-Lead SOIC (7.50 mm)



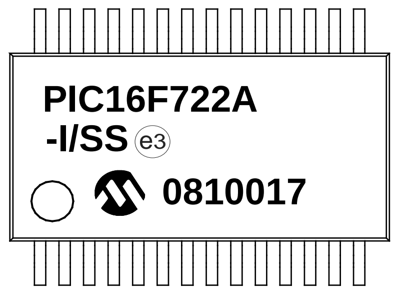
Example



28-Lead SSOP (5.30 mm)



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC® designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

* Standard PICmicro® device marking consists of Microchip part number, year code, week code and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.